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THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:
Hseuh-Chang Wu et al.

Serial No.: 10/753,253

Filed: 01/05/2004

For: RAPID THERMAL COMPENSATION
FOR SEMICONDUCTOR MODULE

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Docket No.: 2003-0440 /
24061.81

Group Art Unit: 3742

Examiner: Fuqua, Shawntina

Conf. No.: 6691

TRANSMITTAL

Mail Stop: AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Enclosed for filing in the above-identified patent application.

1. Amendment in Response to the Office Action dated September 21, 2004;
2. This transmittal (in duplicate); and
3. Return postcard.

The Director is authorized to charge any deficiency fees or credit any overpayments to Deposit Account No. 08-1394 of Haynes and Boone, LLP.

Respectfully submitted,

David M. O'Dell
Registration No. 42,044

Date: 12-13-04

HAYNES AND BOONE, LLP
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File: 24061.81

CERTIFICATE OF MAILING	
I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner For Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated below:	
<u>Bonnie Boyle</u> Bonnie Boyle	
<u>12-13-04</u> Date	



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AMENDMENT

Sir:

In response to the Office action of September 21, 2004, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.